PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6193311

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YAN LI	07/06/2020
SONG GUO	07/06/2020
MOHD KAMRAN AKHTAR	07/06/2020
ALEX J. SCHRINSKY	07/09/2020

RECEIVING PARTY DATA

Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY
Internal Address:	MAILSTOP 1-507
City:	BOISE
State/Country:	IDAHO
Postal Code:	83707-0006

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16924995

CORRESPONDENCE DATA

Fax Number: (801)531-9168

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 801-532-1922

Email: djpfeil@traskbritt.com

Correspondent Name: TRASK BRITT, P.C./ MICRON TECHNOLOGY

Address Line 1: P.O. BOX 2550

Address Line 4: SALT LAKE CITY, UTAH 84110

ATTORNEY DOCKET NUMBER:	2269-15411(2019-2034.00)
NAME OF SUBMITTER:	ELIZABETH HERBST SCHIERMAN
SIGNATURE:	/Elizabeth Herbst Schierman/
DATE SIGNED:	07/09/2020

Total Attachments: 8

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PATENT REEL: 053167 FRAME: 0735

506146580

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, each undersigned ASSIGNOR does hereby:

SELL, ASSIGN AND TRANSFER to MICRON TECHNOLOGY, INC.

("ASSIGNEE"), a corporation of the State of Delaware, having a place of business at 8000 South Federal Way, Mailstop 1-507, Boise, ID 83707-0006, the entire right, title and interest for the United States and all foreign countries in and to any and all improvements that are disclosed in the Application for United States Letters Patent that has been executed by each undersigned ASSIGNOR concurrently herewith, and titled METHODS OF FORMING A MICROELECTRONIC DEVICE STRUCTURE, AND RELATED APPARATUSES AND ELECTRONIC SYSTEMS, such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent or the legal equivalent thereof that have been or may be filed in the United States and all foreign countries relating to any of such improvements; all original, reexamined and reissued patents that have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application made in the United States;

AUTHORIZE the ASSIGNEE to apply for and receive any and all United States and foreign patents relating to such improvements in its own name;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to and in the name of the ASSIGNEE;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement or encumbrance affecting the rights and property herein conveyed has been or will be made or entered into by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT, when requested and at the expense of the ASSIGNEE, to carry out in good faith the intent and purpose of this Assignment, to execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications relating to any and all such improvements; to execute all rightful oaths, declarations, assignments, powers of attorney and other papers; to communicate to the ASSIGNEE all facts and provide to the ASSIGNEE all documents and things known and accessible to the undersigned relating to such improvements and the history thereof, and testify as to the same in any interference, litigation or other proceeding relating thereto; and generally to do everything possible that the ASSIGNEE shall consider desirable for vesting title to such improvements in the ASSIGNEE, and to secure, maintain, defend and enforce valid and enforceable patent protection for such improvements;

ASSIGNOR(S):		
/Yan Li/	Date: _	07/06/2020
Yan Li Residing at: 4358 S Cruzatte Ln, Boise, ID 83716		
Song Guo	Date:	
Residing at: 10814 West Alfina Drive, Boise, ID 83709		
Mohd Kamran Akhtar Residing at: 6160 East Settlement Court, Boise, ID 83716	Date:	
Alex J. Schrinsky Residing at: 2320 North 21 Street, Boise, ID 83702	Date:	

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MICROELECTRONIC DEVICE STRUCTURE, AND RELATED APPARATUSES AND ELECTRONIC SYSTEMS, such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent or the legal equivalent thereof that have been or may be filed in the United States and all foreign countries relating to any of such improvements; all original, reexamined and reissued patents that have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application made in the United States;

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/Alex J. Schrinsky/ Alex J. Schrinsky	Date:	07/09/2020

Residing at: 2320 North 21 Street, Boise, ID 83702